

REMARKS

Claims 1-13 are pending in the application, with claims 1, 4, 7 and 11 being independent. Claims 1, 4, 7, and 11 have been amended. Support for the amendment to claims 1 and 4 may be found, for example, in Fig. 1D and the accompanying text, and support for the amendment to claims 7 and 11 may be found, for example, in Fig. 5B and the accompanying text. No new matter has been introduced.

Claims 1-13 have been rejected as being anticipated by Yamazaki (U.S. Patent Publication 2002/0158288). With respect to claim 1 and its dependent claims, applicant requests reconsideration and withdrawal of this rejection because Yamazaki does not describe or suggest recessing an edge of the mask pattern remaining on the first conductive layer pattern after forming the first conductive layer pattern, as recited in claim 1. In particular, claim 1 recites a process that includes (1) forming a first conductive layer pattern having a tapered edge by etching the second conductive layer and the first conductive layer; (2) after forming the first conductive layer pattern, recessing an edge of the mask pattern remaining on the first conductive layer pattern; and (3) after recessing the edge of the mask pattern, forming a second conductive layer pattern by selectively etching the second conductive layer in the first conductive layer pattern in accordance with the mask pattern. By contrast, Yamazaki, at paragraphs 0083 to 0086, does not describe or suggest the recited step of recessing an edge of the mask pattern remaining on the first conductive layer pattern after forming the first conductive layer pattern. Rather, as noted in the rejection, Yamazaki implies that the edge of the mask pattern is recessed during (rather than after) formation of the first conductive layer pattern. Accordingly, for at least these reasons, the rejection of claim 1 and its dependent claims should be withdrawn.

Similarly to claim 1, independent claim 4 recites (1) forming a first conductive layer pattern having a tapered edge; (2) after forming the first conductive layer pattern, recessing an edge of the mask pattern remaining on the first conductive layer pattern; and (3) after recessing the edge of the mask pattern, forming a second conductive layer pattern by selectively etching the third conductive layer and the second conductive layer in the first conductive layer pattern in

accordance with the mask pattern. As discussed above, Yamazaki does not describe or suggest such an arrangement. Accordingly, for at least this reason, the rejection of claim 4 and its dependent claims should be withdrawn.

Similarly, each of independent claims 7 and 11 recites (1) decreasing a taper angle of an edge of the mask pattern by performing plasma treatment; (2) after decreasing the taper angle, forming a first conductive layer pattern having a tapered edge by etching the second conductive layer and the first conductive layer of the laminate layer by using the mask pattern; and (3) after forming the first conductive layer pattern, forming a second conductive layer pattern by selectively etching the second conductive layer in the first conductive layer pattern. While the rejection indicates that Yamazaki clearly shows such an arrangement in paragraphs 0085 and 0086, this is not the case. Rather, those paragraphs, in combination with paragraph 0084, describe a two-step etching process that does not include decreasing a taper angle of a mask pattern prior to forming a first conductive layer pattern. Accordingly, for at least these reasons, the rejection of claims 7 and 11, and their dependent claims, should be withdrawn.

Applicant submits that all claims are in condition for allowance.

Enclosed is a \$790.00 check for the Request for Continued Examination fee. Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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